



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSC014N06NSSC	<b>Issued</b>	16. May 2021
<b>MA#</b>	MA005349394		
<b>Package</b>	PG-WSON-8-2	<b>Weight*</b>	100.26 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.334	2.33	2.33	23275	23275
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		114	
	non noble metal	zinc	7440-66-6	0.046	0.05		455	
	non noble metal	iron	7439-89-6	0.912	0.91		9093	
	non noble metal	copper	7440-50-8	37.021	36.91	37.88	369234	378896
wire	noble metal	gold	7440-57-5	0.066	0.07	0.07	661	661
encapsulation	organic material	carbon black	1333-86-4	0.037	0.04		371	
	plastics	epoxy resin	-	1.712	1.71		17077	
	inorganic material	silicondioxide	60676-86-0	16.861	16.82	18.57	168167	185615
leadfinish	non noble metal	tin	7440-31-5	1.365	1.36	1.36	13614	13614
plating	noble metal	silver	7440-22-4	0.839	0.84	0.84	8363	8363
solder	noble metal	silver	7440-22-4	0.064	0.06		643	
	non noble metal	tin	7440-31-5	0.129	0.13		1286	
	non noble metal	lead	7439-92-1	2.385	2.38	2.57	23789	25718
heat sink clip	inorganic material	phosphorus	7723-14-0	0.011	0.01		109	
	non noble metal	zinc	7440-66-6	0.044	0.04		437	
	non noble metal	iron	7439-89-6	0.876	0.87		8733	
	non noble metal	copper	7440-50-8	35.552	35.46	36.38	354579	363858
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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